

SN54AHCT16245, SN74AHCT16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCLS335J – MARCH 1996 – REVISED OCTOBER 2000

- Members of Texas Instruments' Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17

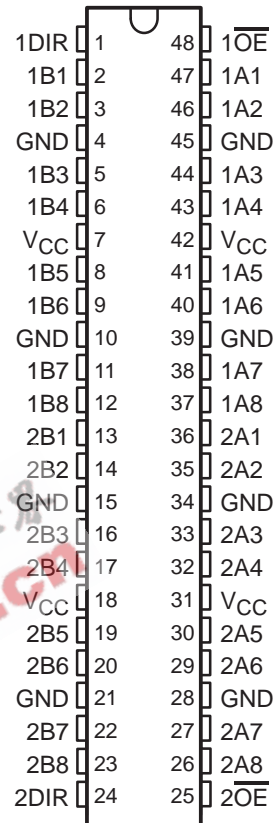
description

The 'AHCT16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54AHCT16245 . . . WD PACKAGE
SN74AHCT16245 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74AHCT16245DL	AHCT16245
		Tape and reel	SN74AHCT16245DLR	
	TSSOP – DGG	Tape and reel	SN74AHCT16245DGGR	AHCT16245
-55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHCT16245DGVR	HF245
	CFP – WD	Tube	SNJ54AHCT16245WD	SNJ54AHCT16245WD

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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 **TEXAS
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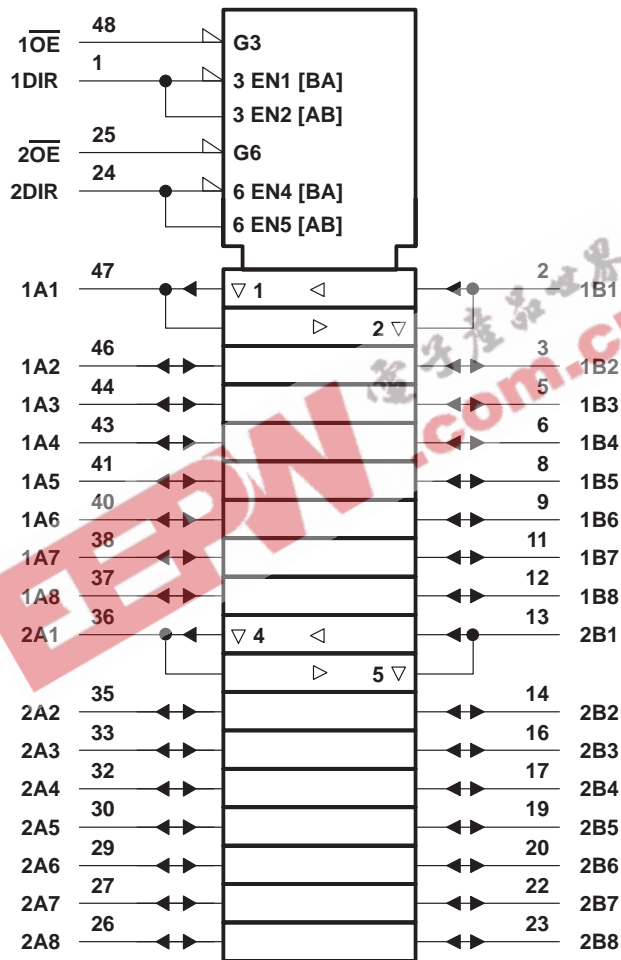
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FUNCTION TABLE
(each 8-bit transceiver)

INPUTS		OPERATION
OE	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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SCLS335J – MARCH 1996 – REVISED OCTOBER 2000

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT16245		SN74AHCT16245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1			0.1	V	
	I _{OL} = 8 mA				0.36		0.44	0.44		
I _I	$\overline{\text{OE}}$ or DIR	V _I = V _{CC} or GND	0 V to 5.5 V					±1*	μA	
I _{OZ} †	A or B inputs	V _O = V _{CC} or GND	5.5 V					±2.5	μA	
I _{CC}		V _I = V _{CC} or GND, I _O = 0	5.5 V					40	μA	
ΔI _{CC} ‡		One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V					1.5	mA	
C _i	$\overline{\text{OE}}$ or DIR	V _I = V _{CC} or GND	5 V					10	pF	
C _{io}	A or B inputs	V _I = V _{CC} or GND	5 V					4	pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† For I/O ports, the parameter I_{OZ} includes the input leakage current.

‡ This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHCT16245		SN74AHCT16245		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	C _L = 15 pF	4.5**	8.5**		1**	10**	1	9.5	ns
t _{PHL}				4.5**	8.5**	1**	10**	1	9.5		
t _{PZH}	$\overline{\text{OE}}$	A or B	C _L = 15 pF	8.9**	13**		1**	14**	1	14	ns
t _{PZL}				8.9**	13**	1**	14**	1	14		
t _{PHZ}	$\overline{\text{OE}}$	A or B	C _L = 15 pF	9.2**	14**		1**	15**	1	15	ns
t _{PLZ}				9.2**	14**	1**	15**	1	15		
t _{PLH}	A or B	B or A	C _L = 50 pF	7	9.5		1	11	1	10.5	ns
t _{PHL}				5.3	9.5	1	11	1	10.5		
t _{PZH}	$\overline{\text{OE}}$	A or B	C _L = 50 pF	8.3	14		1	15	1	15	ns
t _{PZL}				8.3	14	1	15	1	15		
t _{PHZ}	$\overline{\text{OE}}$	A or B	C _L = 50 pF	8	14		1	15	1	15	ns
t _{PLZ}				8	14	1	15	1	15		
t _{sk(o)}			C _L = 50 pF			1***			1	ns	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

*** On products compliant to MIL-PRF-38535, this parameter does not apply.

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SN54AHCT16245, SN74AHCT16245
16-BIT BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS

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noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER	SN74AHCT16245			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.6		V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		-0.6		V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}		4.8		V
$V_{IH(D)}$ High-level dynamic input voltage	2			V
$V_{IL(D)}$ Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

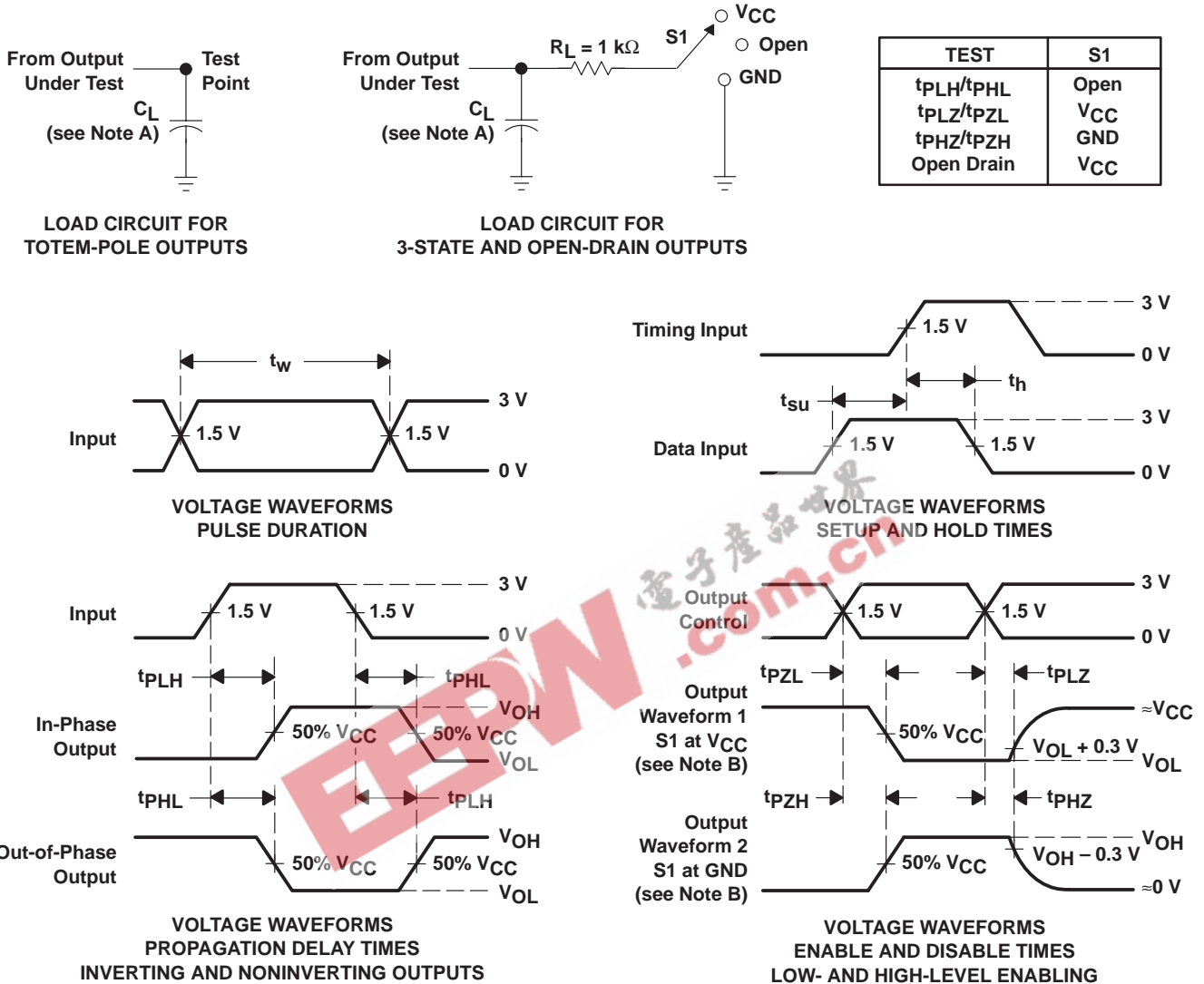
PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	17	pF

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AHCT16245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16245DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHCT16245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16245DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

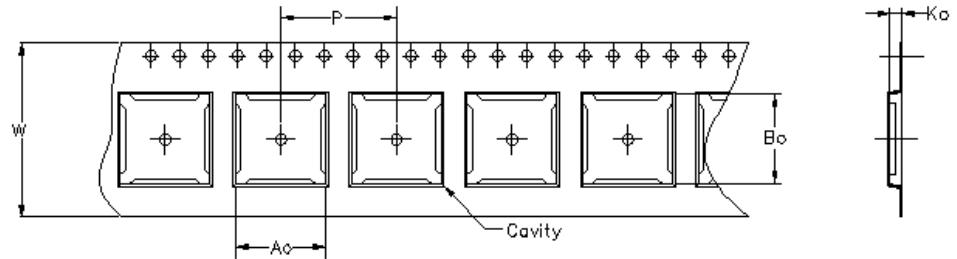
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

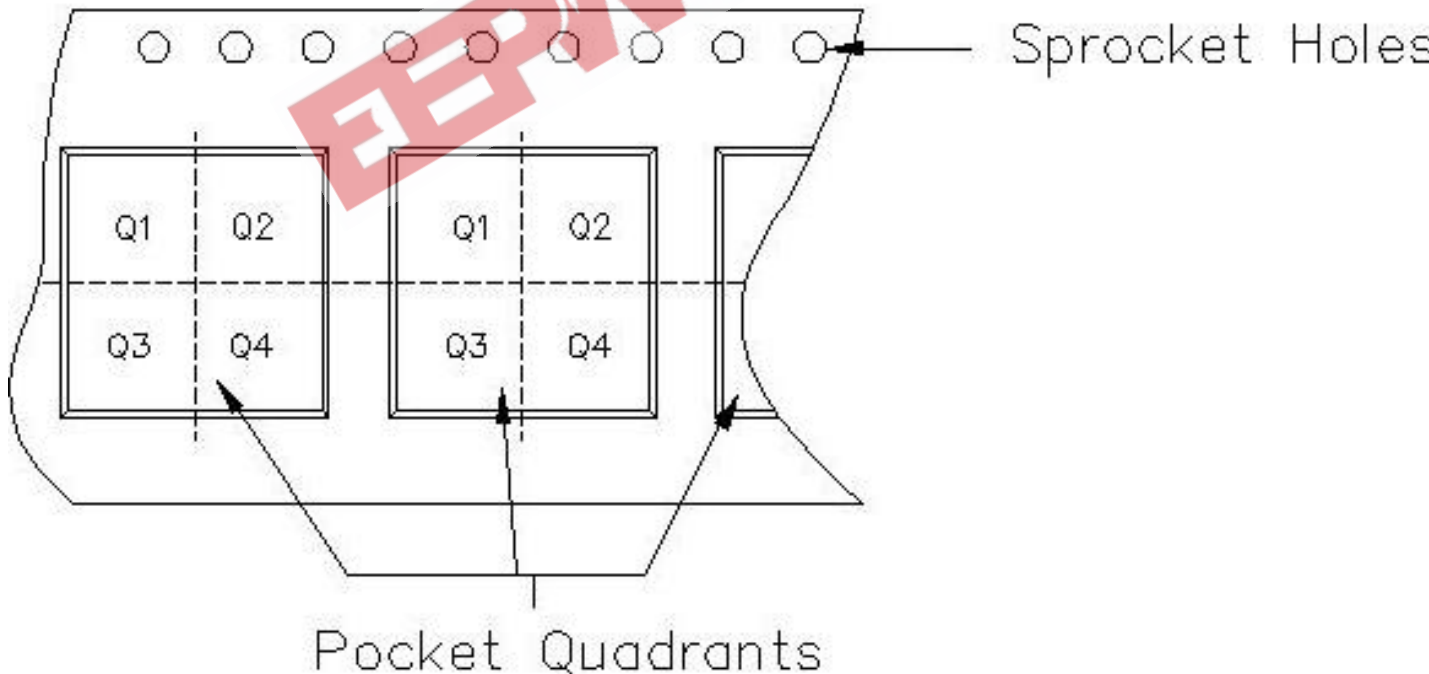
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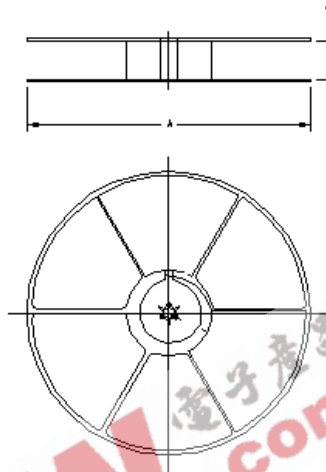
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



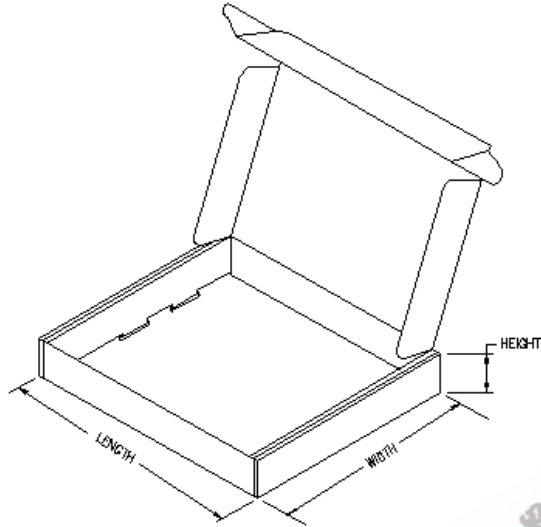
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT16245DGGR	DGG	48	MLA	330	24	8.6	15.8	1.8	12	24	Q1
SN74AHCT16245DGVR	DGV	48	MLA	330	24	6.8	10.1	1.6	12	24	Q1
SN74AHCT16245DLR	DL	48	MLA	330	32	11.35	16.2	3.1	16	32	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AHCT16245DGGR	DGG	48	MLA	333.2	333.2	31.75
SN74AHCT16245DGVR	DGV	48	MLA	333.2	333.2	31.75
SN74AHCT16245DLR	DL	48	MLA	336.6	342.9	41.3



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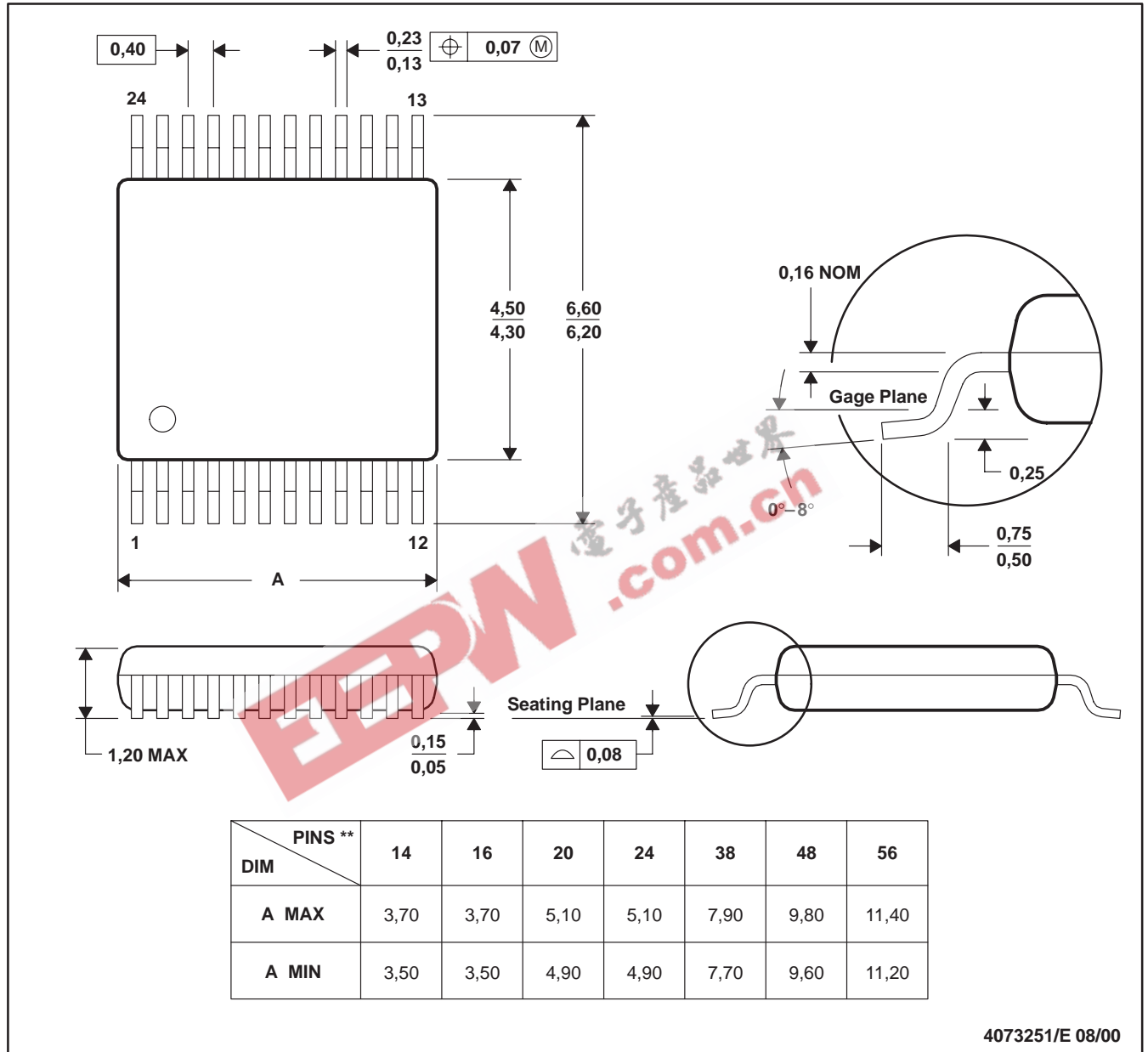
MECHANICAL DATA

MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

DGV (R-PDSO-G)**

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

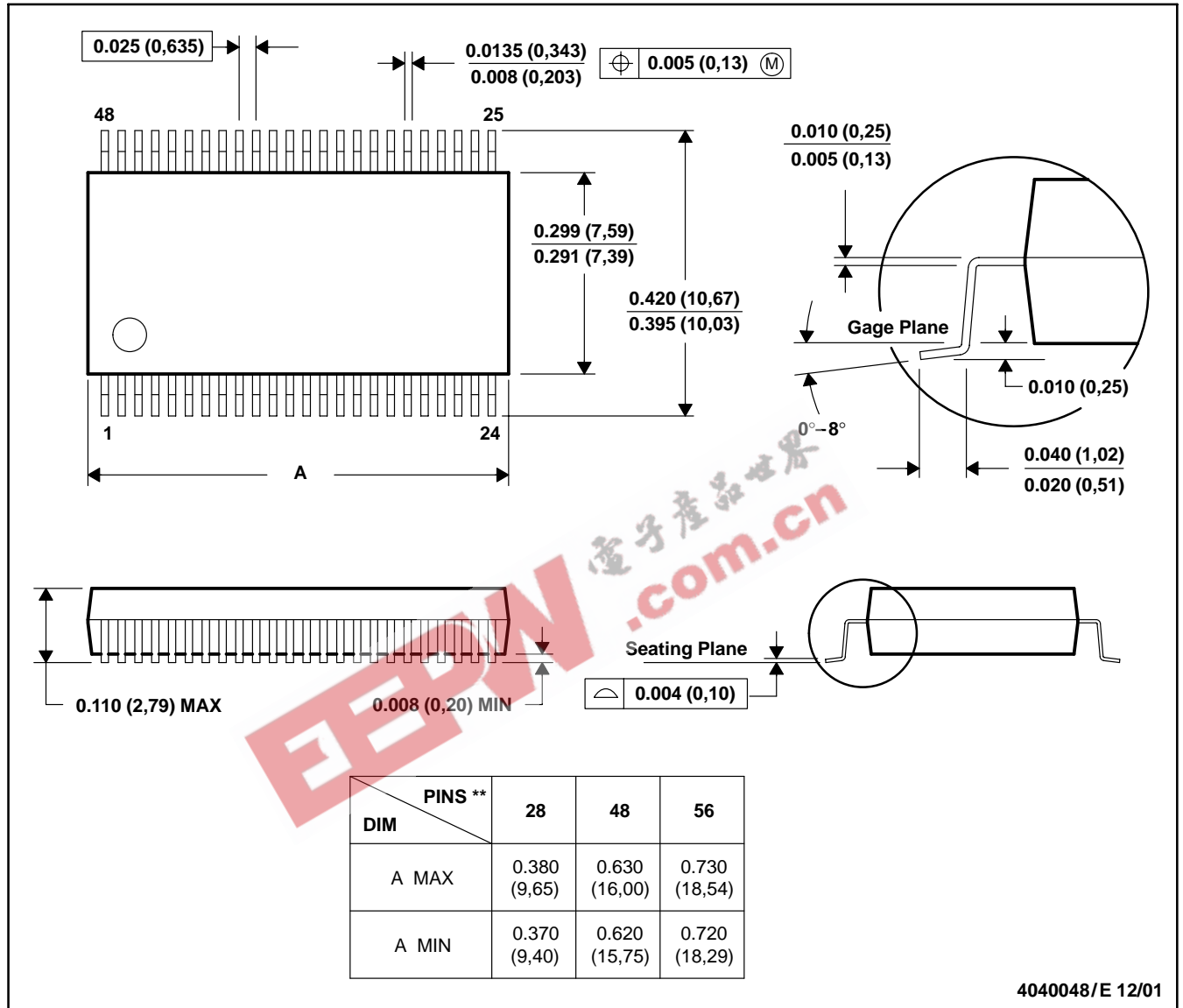
MECHANICAL DATA

MSS0001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

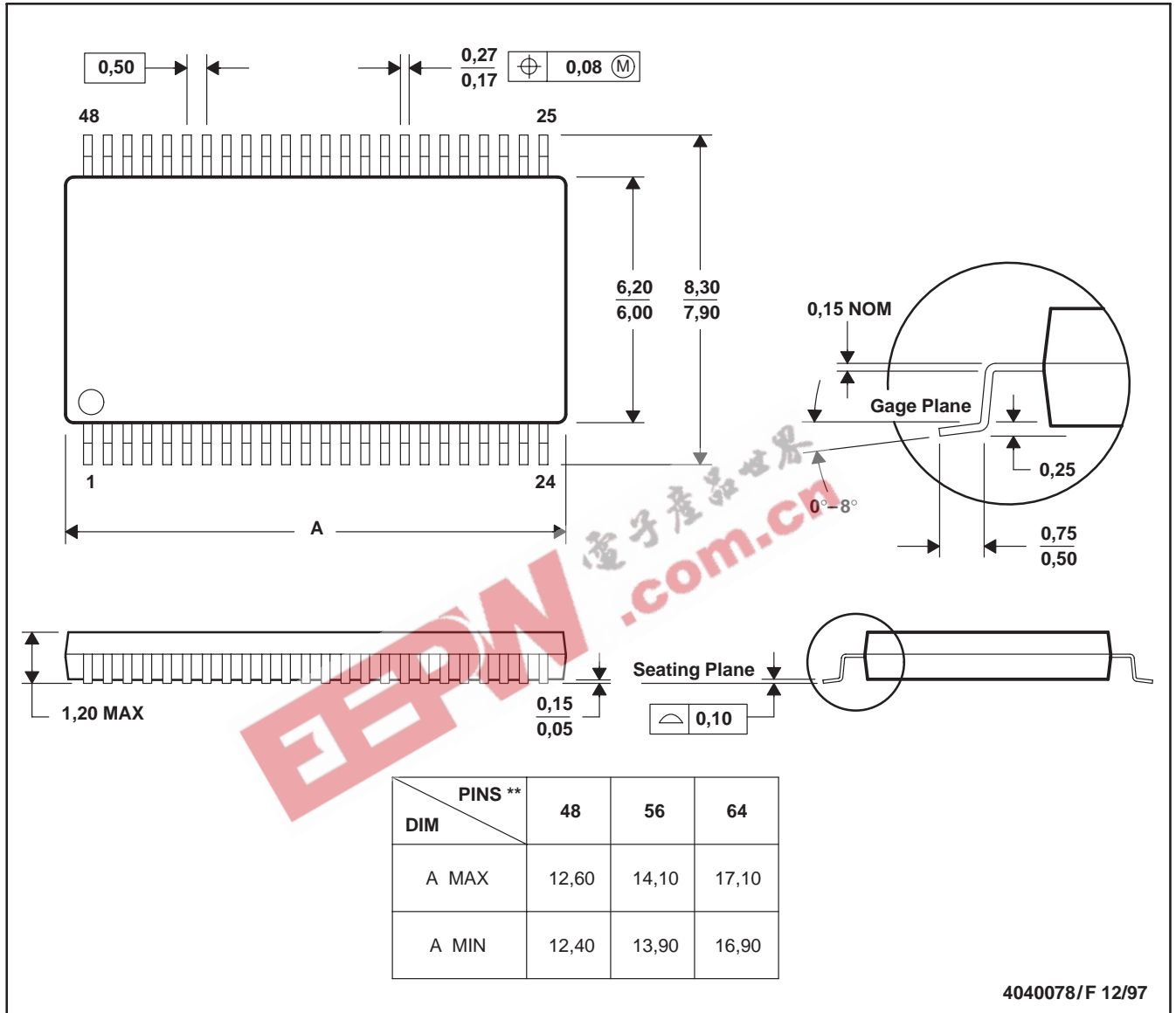
MECHANICAL DATA

MTSS003D – JANUARY 1995 – REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-153

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